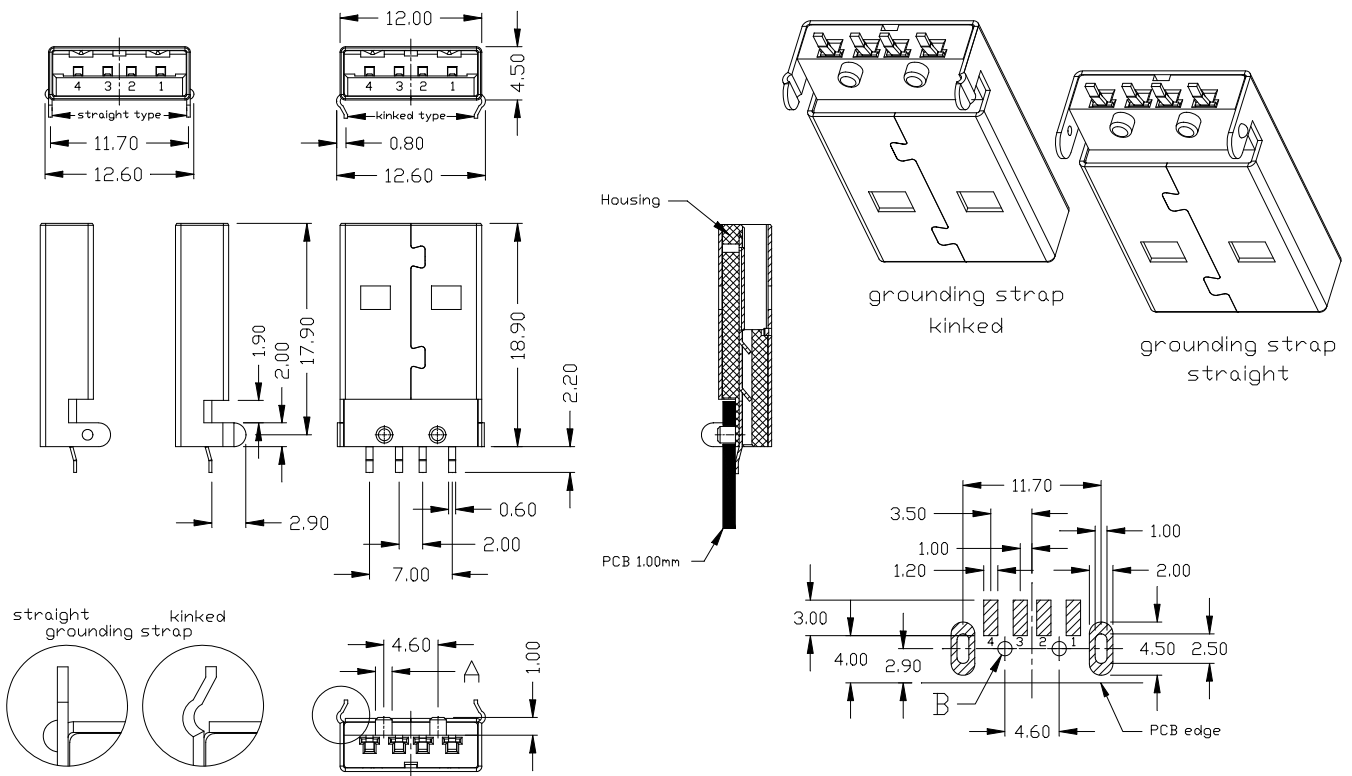


SMT Type



Recommendation:

DIM. "B" =  $\varnothing$  1,20mm if locating peg  $\varnothing$  "A"=1,00mm

DIM. "B" =  $\varnothing$  1,60mm if locating peg  $\varnothing$  "A"=1,40mm

ORDER CODE

USP - B 04 - SA x x - XX

Housing Colour

Black (Standard) = B  
others on request

USB Corresponding

1 - 95 = USB 1.0 corresponding

2 - 98 = USB 2.0 corresponding

Execution

0 = kinked grounding pins; locating pegs  $\varnothing$ 1.00mm

1 = straight grounding pins; locating pegs  $\varnothing$ 1.00mm

2 = kinked grounding pins; locating pegs  $\varnothing$ 1.40mm

3 = straight grounding pins; locating pegs  $\varnothing$ 1.40mm

( for locating peg dim. pls. go to drawing DIM. "A" )

Specification

Material

Contact (RoHS compliant)	Brass
Plating:	
Contact area	Au flash over Ni (USB 1.0 corresponding) Au 30 $\mu$ over Ni (USB 2.0 corresponding)
Solder area	Sn (leadfree)
Housing (RoHS compliant)	Nylon UL 94-V0
Shell (RoHS compliant)	brass, 80 $\mu$ "-120 $\mu$ " Ni plated

Mechanical

Mating cycles	1.500 min.
SMT coplanarity	0.10mm

Electrical

Current rating	1 A max. 1 Contact (Signal only)
Voltage rating	30V AC (rms)
Withstanding voltage	750V AC (rms) 1 Minute (USB 1.0) 500V AC (rms) 1 Minute (USB 2.0)
Insulation resistance	1.000M $\Omega$ min. (500V DC)
Contact resistance	30m $\Omega$ max.

Others

Operating temperature	-55° C to +85° C
Processing temperature	+260° C for 10 sec. max.